

Feedback – Si process & integration

#	Name	Subject	Prime	Contact
01		65-45nm rf analog & power rf PDSOI		ST (D. Thomas)
02		28nm CMOS: Uttermost Phase 2	IFX	
03		28nm LP FDSOI CMOS		ST (D. Thomas)
04		28nm rf CMOS (depending on Mirandella)		IFX (W. Dettmann)
05		22nm early research (incl. FDSOI)		IFX & ST
06		e-memory “cheap” scheme (1TDRAM, etc.)		ST (D. Thomas)
07		e-memory architecture for low power		ST (D. Thomas)
08		e-PCM		Numonyx (L. Baldi)
09		9D-sense	Bosch	P. van Staa
10		rf mm-wave to THz		ST (D. Thomas)
11		application-oriented image sensor		ST (D. Thomas)
12		FE – BE interface		IFX (W. Dettmann)
13		Design kit for 3D integration		ST (G. Casanova)
14		DFT for 3D	FEI	L. Kwakman
15		3D integrated passive rf / opto / etc.	ST-E	P. Bleuet

Related to on-going projects / funding discussions
see “Wireless SP”

ST = dominique.thomas@st.com; gilles.casanova@st.com; IFX = wolfgang.dettmann@infineon.com
 Numonyx = livio.baldi@numonyx.com; Bosch = Peter.vanStaa@de.bosch.com;
 FEI = laurens.kwakman@fei.com; ST-E = patrick.blouet@stericsson.com